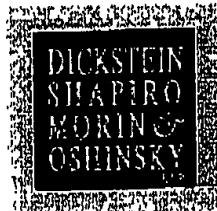


FAX TRANSMISSION



DATE: December 4, 2001
CLIENT NO.: M4065.0184
MESSAGE TO: Examiner Chuong A. Luu
COMPANY: U.S. Patent and Trademark Office, Art Unit 2825
FAX NUMBER: 703-308-7722
PHONE: 703-305-0129
FROM: Mark J. Thronson
PHONE: (202) 775-4742

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PAGES (Including Cover Sheet): 5

HARD COPY TO FOLLOW: YES NO

Please file the attached Amendment in U.S. Patent Application No. 09/594,510. Please charge any deficiencies in the fees to Deposit Account No. 04-1073.

Applicants' undersigned representative hereby certifies, pursuant to 37 C.F.R. § 1.8, that the attached Amendment is being transmitted by facsimile to the U.S. Patent and Trademark Office on December 4, 2001.

Mark J. Thronson, Reg. No. 33,082

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Docket No.: M4065.0184/P184
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Alan G. Wood et al.

Application No.: 09/594,510

Group Art Unit: 2825

Filed: June 16, 2000

Examiner: C. Luu

For: SEMICONDUCTOR DEVICE PACKAGE
AND METHOD

6/14 Andb
12/7/01
A. Walli

AMENDMENT

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Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

DEC 4 - 2001

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Dear Sir:

In response to the Office Action dated September 4, 2001, please amend the
above-identified U.S. Patent application as follows:

IN THE CLAIMS:

Rewrite claim 11 as follows:

11. (Amended) A method of making semiconductor device packages,
comprising:
forming a layered assembly by attaching a semiconductor wafer and a stiff metal
layer to a dielectric layer;